

ABSTRACT

In order to ensure manufacturability of electronic circuits with conductor strips having a copper width of over 105 microns, a new series of patterns has been designed for each of the components. A copper surface has been added to said components to receive the adhesive drops thereby compensating for the height difference if the copper surface is bigger than 105 microns. If the width of the areas of the electronic component which are to be connected to the conductive coating of the printed circuit had a width a_1 , the width according to the invention is now a_2 , thereby making it possible to deposit the corresponding adhesive material in said strip having width a_2 .